

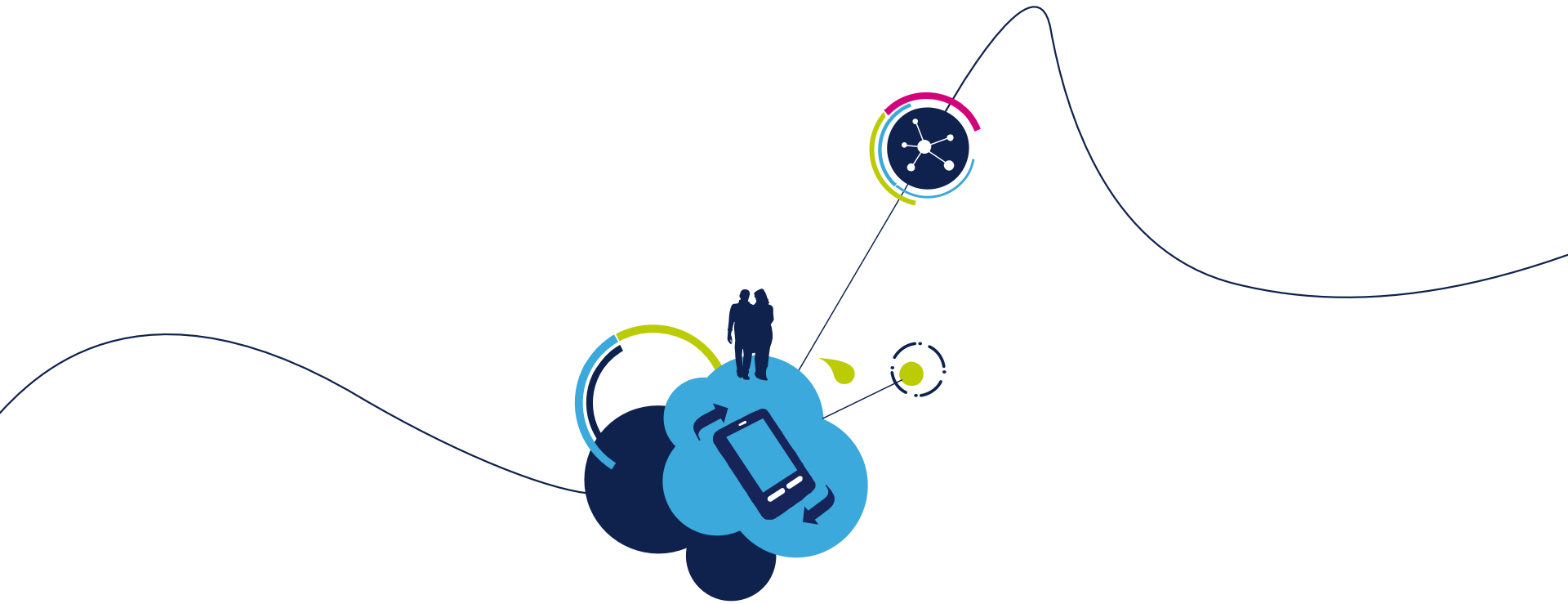
Thin metal film 4H-SiC vertical Schottky photodiodes for UV Index monitoring

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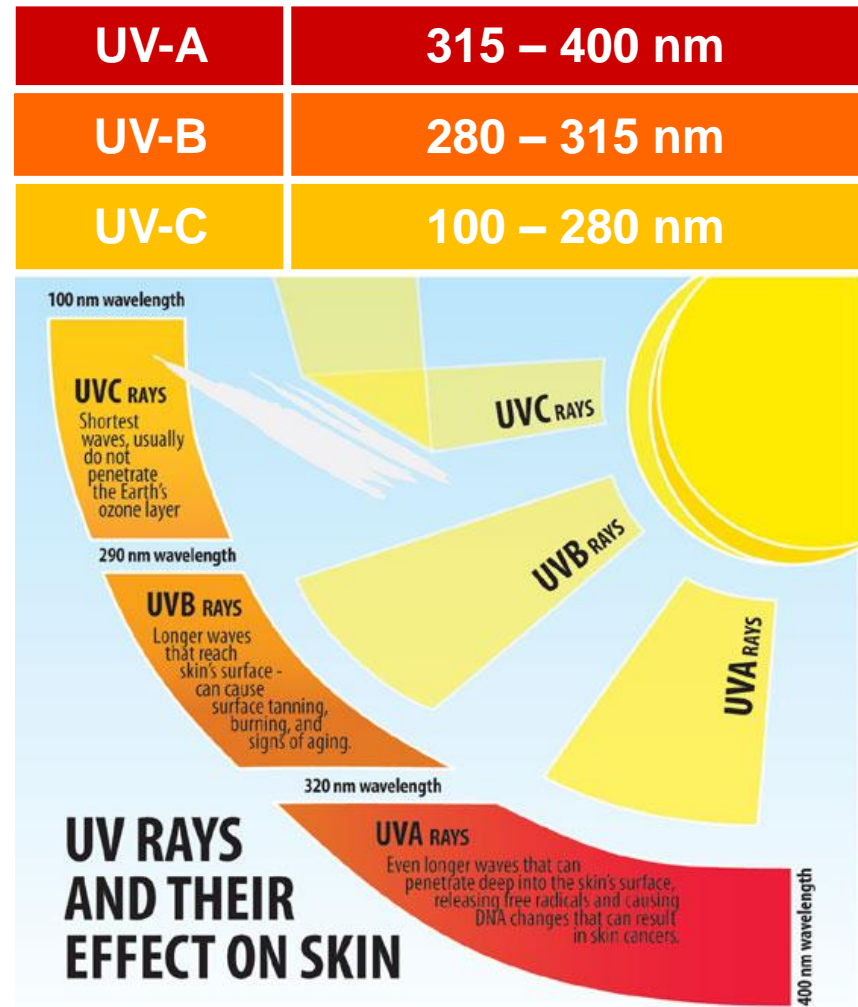
- Introduction
- Photodiode fabrication
- Morphological characterization
- Electro-optical characterization
- Conclusions



Introduction

The ultraviolet region

- The UV region covers the wavelength range 100 - 400 nm
- As sunlight passes through the atmosphere, all UV-C and about 90% of UV-B radiation are absorbed
- The UV radiation reaching the Earth's surface is composed of UV-A with a small UV-B component
- An excessive exposure to UV radiation may cause acute and chronic adverse health effects to skin and eye



- The UV Index (UVI) describes the degree of dangerousness of solar UV radiation at the Earth's surface

- It is defined as

$$UVI = K_{er} \int_{250 \text{ nm}}^{400 \text{ nm}} S_{er}(\lambda) E_{\lambda} d\lambda$$

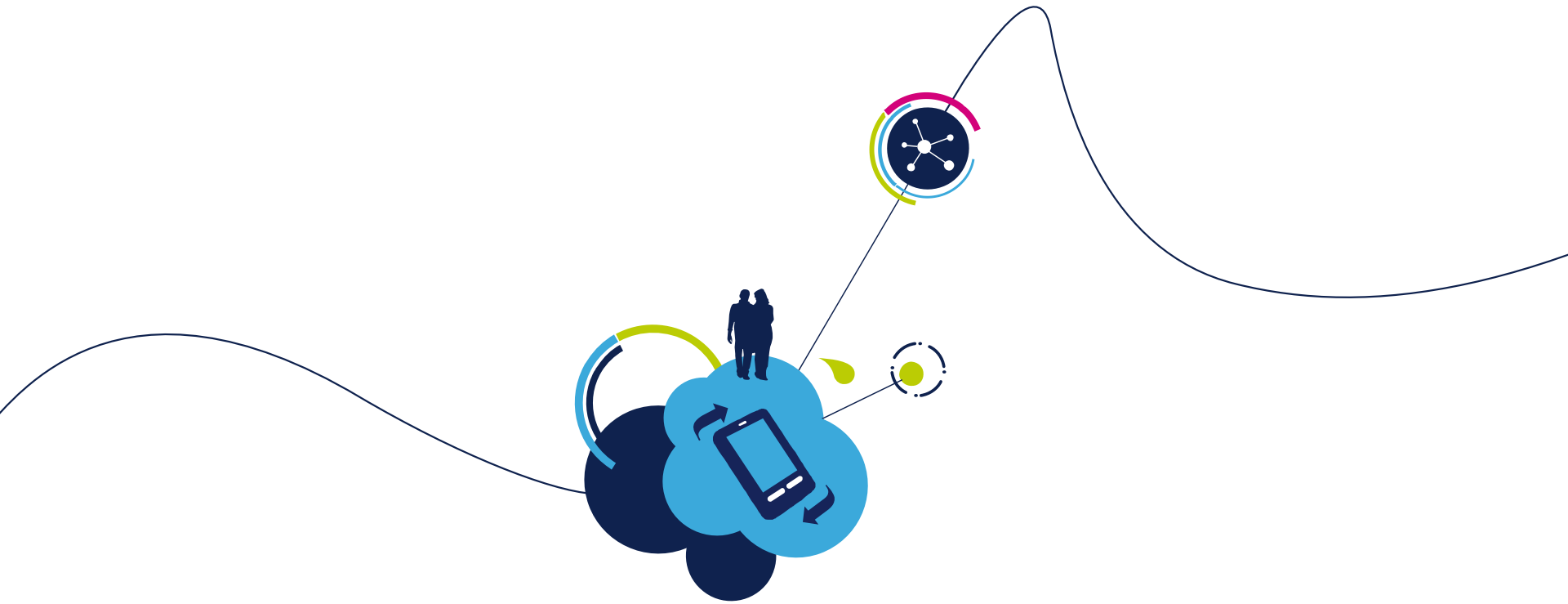
- UVI is closely related to sun elevation, latitude, cloud cover, altitude, ozone and ground reflection
- For simplicity it is divided into different levels

UV Index	Exposure level
0 – 2	Low
3 – 5	Moderate
6 – 7	High
8 – 10	Very high
11+	Extreme

The UV Index monitoring

- Photodetection in the UV region has drawn extensive attention owing to its application in biological and medical fields
- We propose a vertical 4H-SiC Schottky based detector operating in photovoltaic regime and coupled to an appropriate IC interface for the realization of an ultra-compact UVI sensor





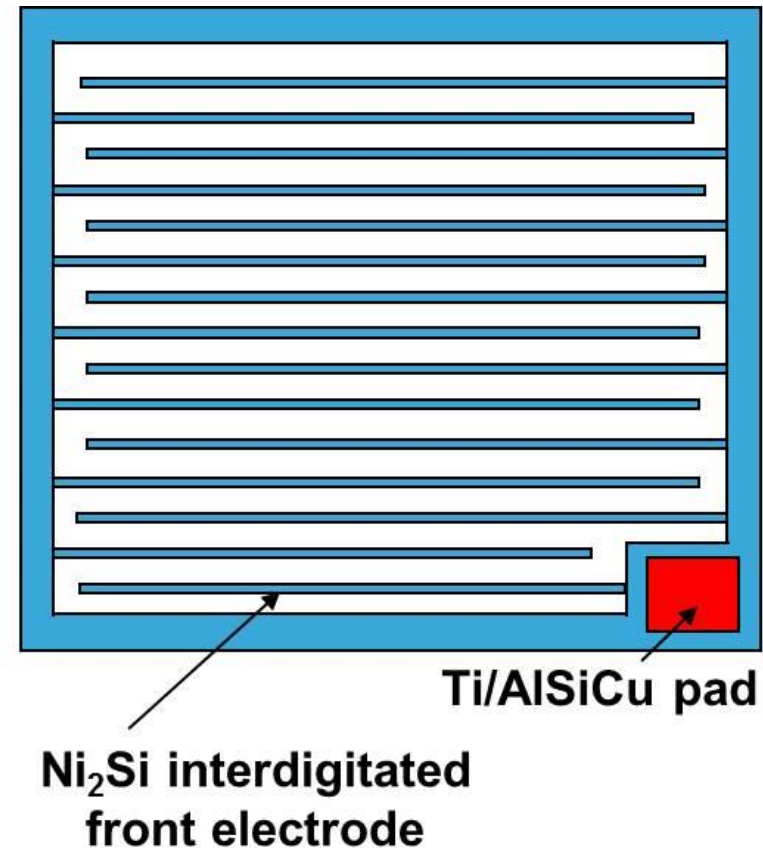
Photodiode fabrication

Previous generation - Interdigitated

- In the previous years a vertical 4H-SiC Schottky UV detector, based on the pinch-off surface effect, obtained by means of Ni_2Si interdigitated contacts, has been developed

Drawbacks

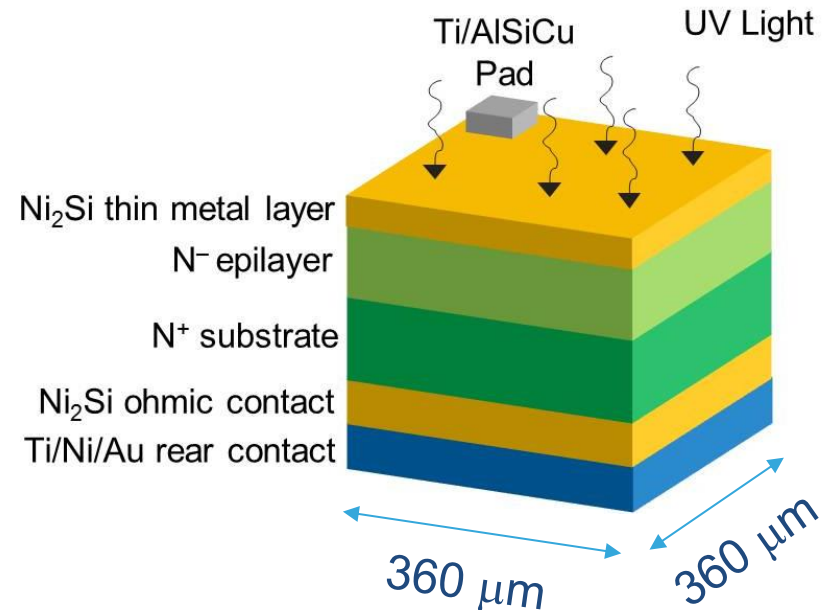
- Difficulty to define with good reproducibility the width of the thin metal stripes
- Pinch-off affected by charge effects due to direct exposure of 4H-SiC surface

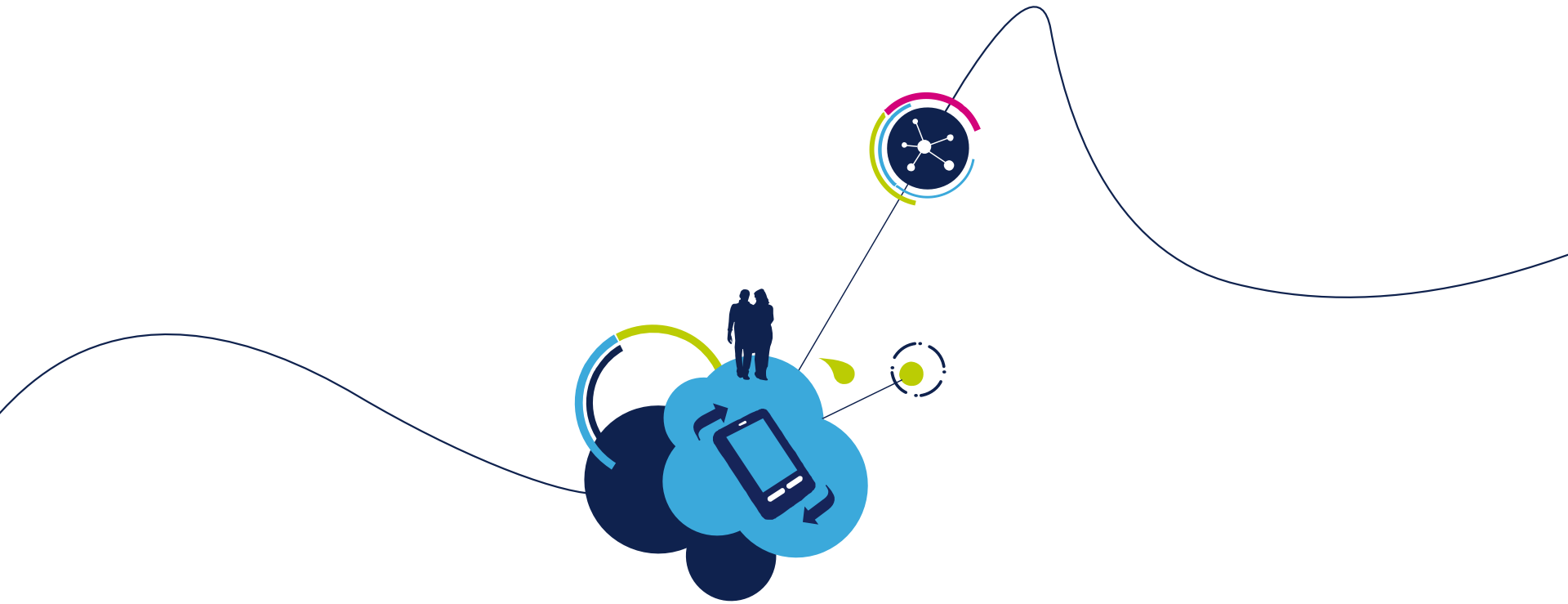


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Adopted solution - Semitransparent metal

- An alternative solution, based on a Schottky contact realized through a continuous thin Ni_2Si film has been proposed
- Ni_2Si front layer has to be as thin as possible to guarantee a higher transmission in the UV range (10 nm Ni deposited; 20 nm silicide after RTP)
- Very low doping ($8 \times 10^{13} \text{ cm}^{-3}$) epilayer is required to have the maximum detection efficiency at 0 V
- A sensitive area of $0.36 \times 0.36 \text{ mm}^2$ has been chosen

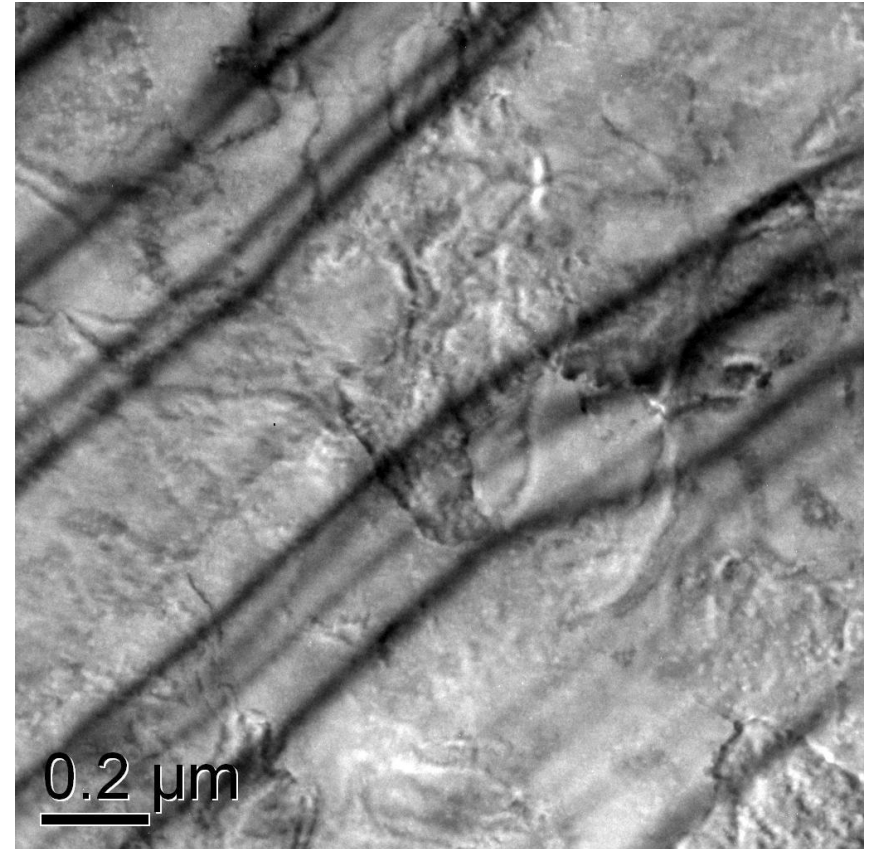




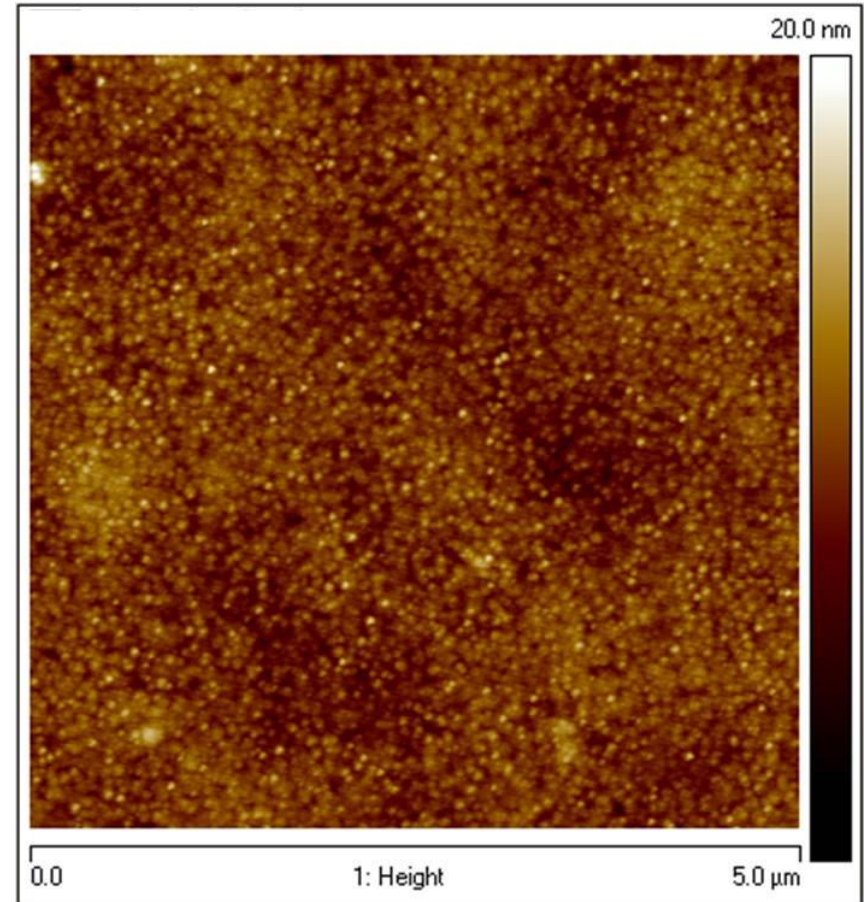
Morphological characterization

Plan view TEM analyses

- First of all the continuity of Ni_2Si film has been verified by means of plan view TEM analyses
- The fringes visible in this micrograph are due to the sample preparative, that gives a radial gradient of sample thickness

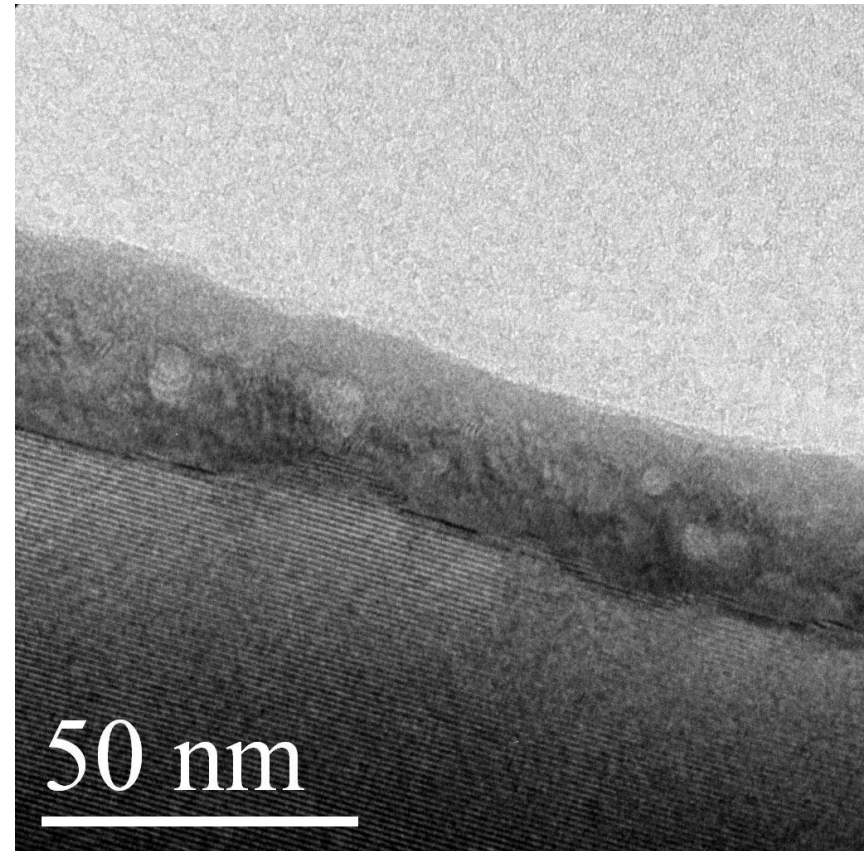


- The surface of Ni₂Si film has also been investigated by means of AFM
- The film is uniform and exhibits low roughness. The value of RMS is 1.52 nm



Cross sectional TEM analyses

- The cross sectional TEM micrograph show a continuous Ni_2Si layer about 20 nm thick
- Carbon clusters at the $\text{Ni}_2\text{Si}/4\text{H-SiC}$ interface and on the middle-bottom portion of the Ni_2Si layer are clearly visible
- These clusters are due to the segregation of residual carbon coming from the reaction between silicon and the metallic Ni



Cross sectional EFTEM chemical maps

- All the deposited Ni has reacted with the Si gathered from SiC epitaxial layer



C

50 nm



Ni

50 nm

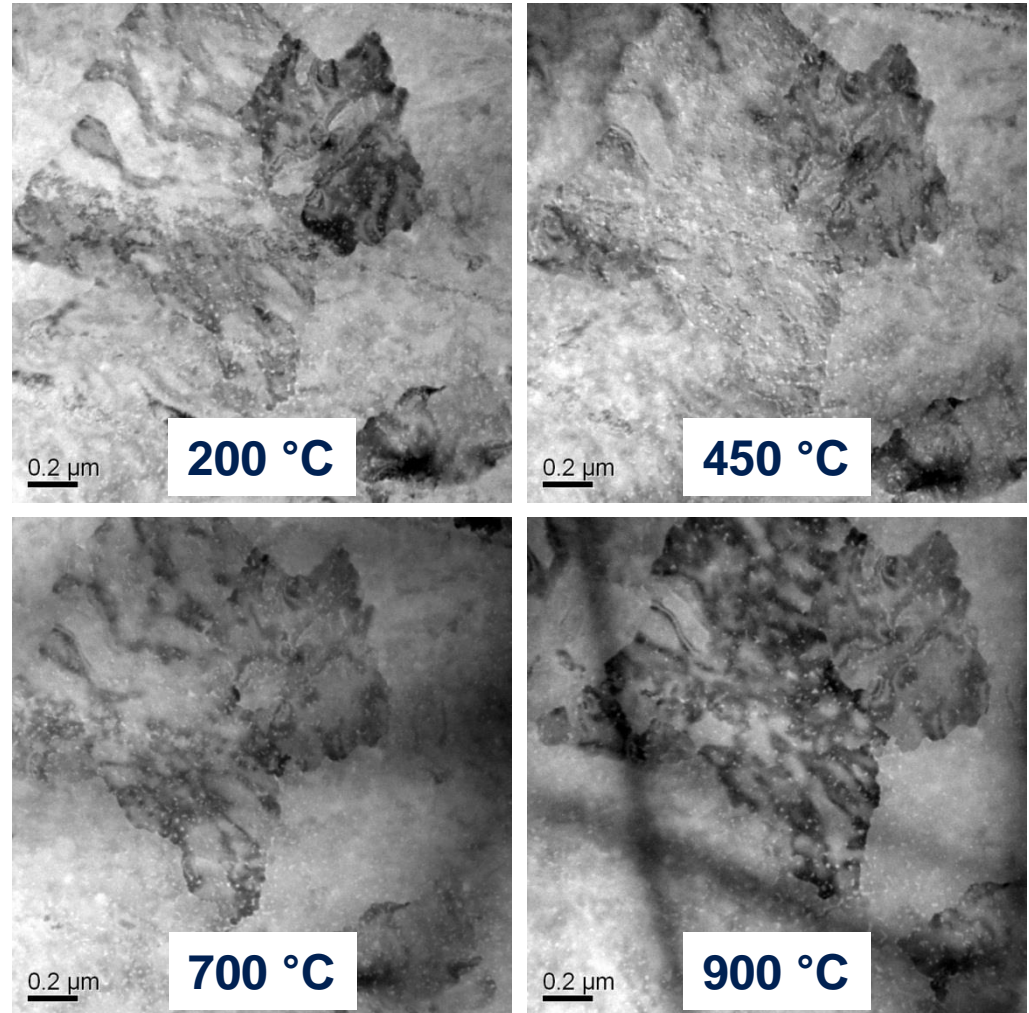


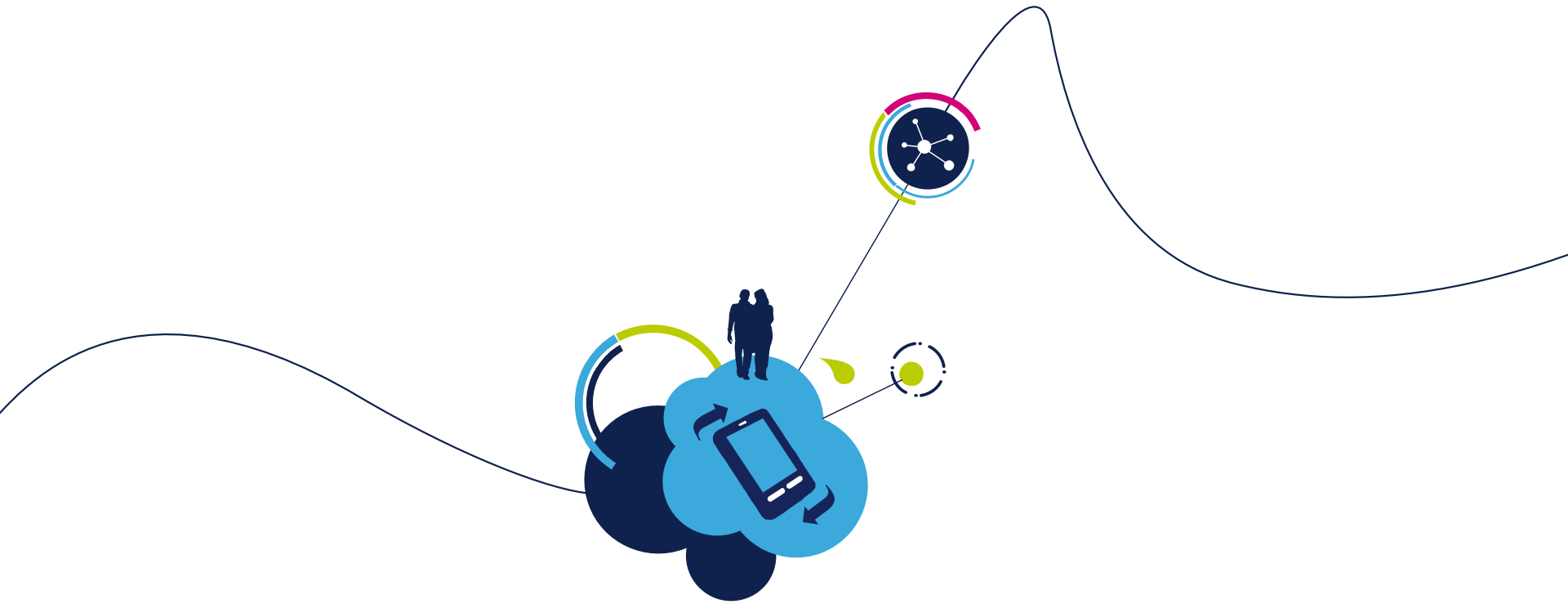
Si

50 nm

TEM analyses with *in-situ* thermal treatment

- TEM analyses with *in-situ* treatment has been performed, rising the temperature from 200 °C up to 900 °C, with step of 50 °C and 15 minutes
- Any significant change of grains shape or grains boundaries has been observed
- The semitransparent metal barrier exhibits a good thermal stability

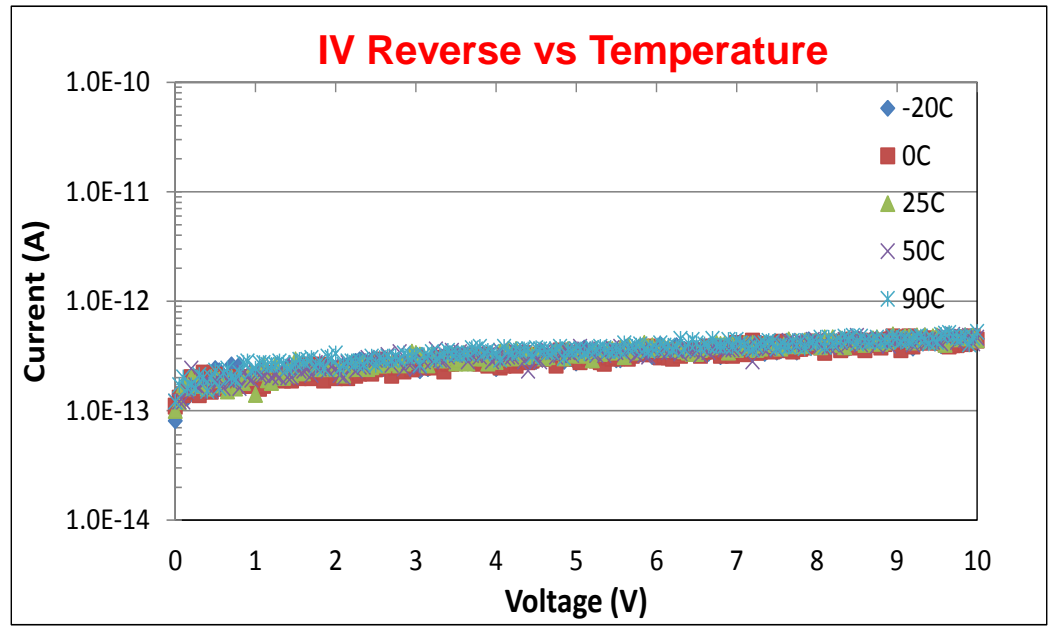




Electro-optical characterization

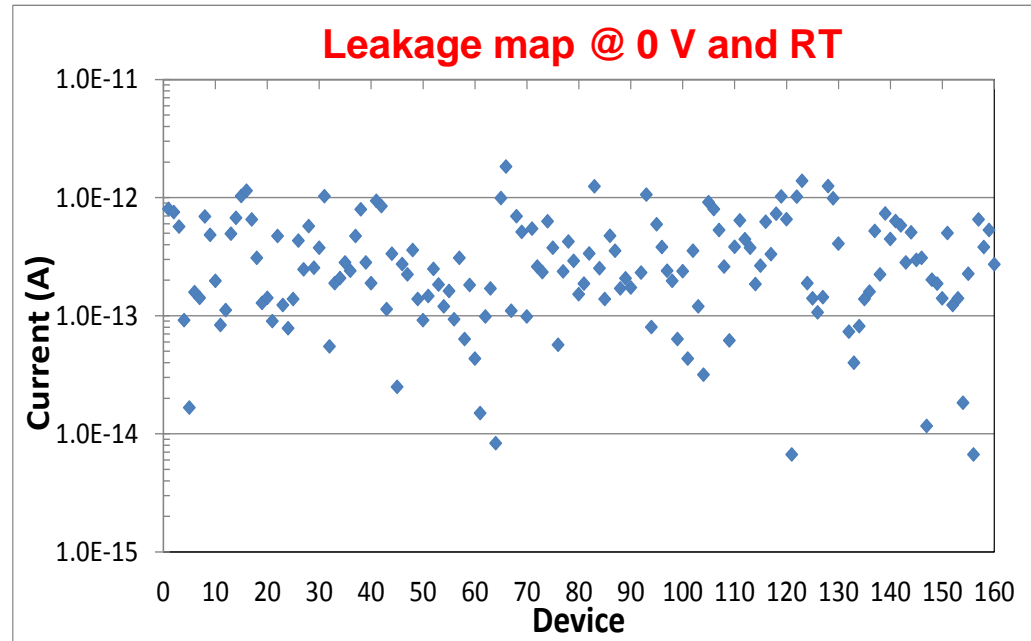
Leakage as a function of Temperature

- Low leakage current (<1 pA) measured also at high temperature
- High signal to noise ratio
- High efficiency also for very low UV photocurrent levels



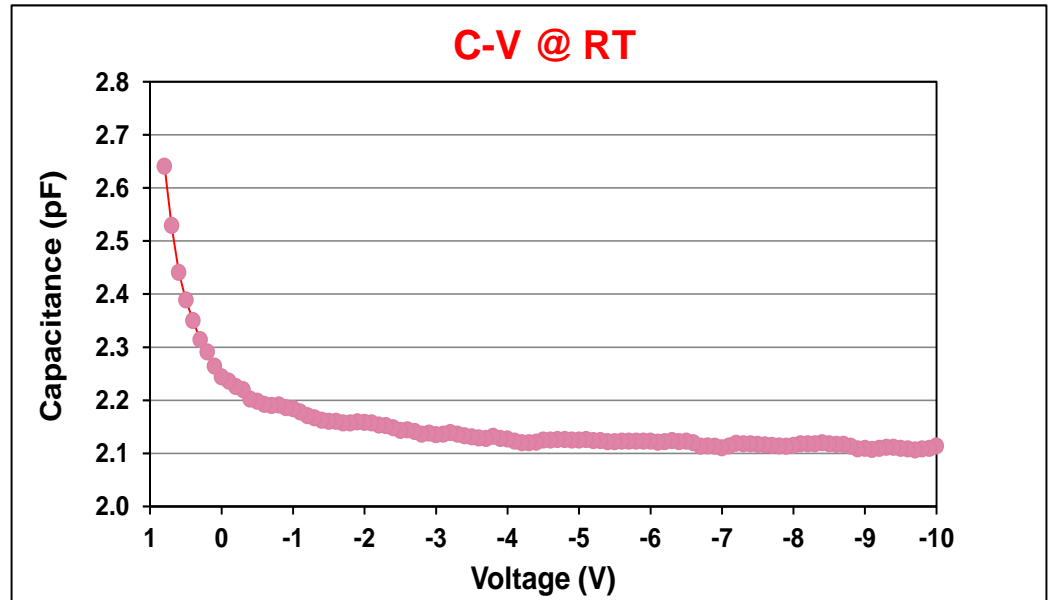
Map of leakage

- Leakage has been measured at 0 V and room temperature on 168 devices on a wafer
- Good uniformity of performance with very low values (approximately <1 pA)



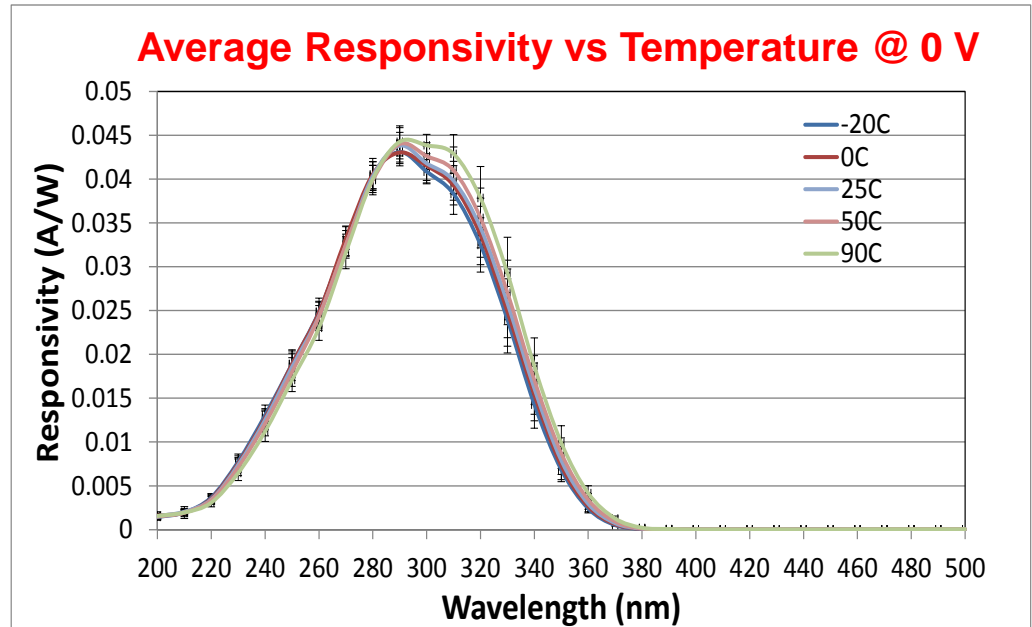
C-V characteristic

- Capacitance has been measured at room temperature as a function of the applied reverse voltage
- The capacitance does not decrease significantly when we move from 0 V to increasing reverse bias applied to the device
- The low doped epilayer is depleted at 0 V



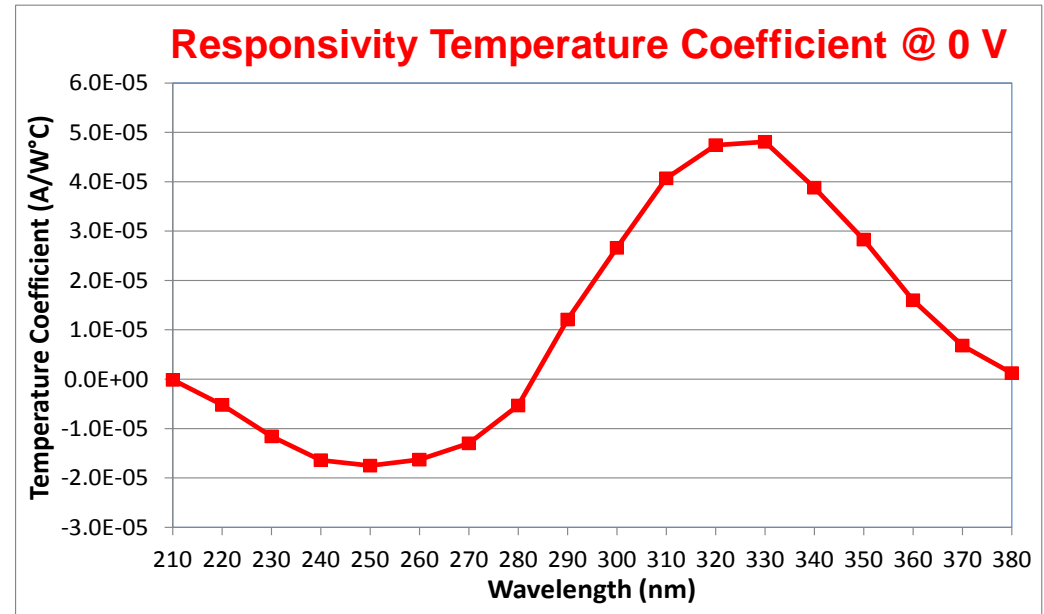
Responsivity @ 0 V

- Responsivity has been measured in photovoltaic operation condition
- Good optical response, also at low wavelengths, enabling an optimal wavelength match with erytema curve
- For a such sensitive area, a peak responsivity value in the range 0.035-0.05 A/W is required
- *Visible blindness* about 10^{-4}



Temperature Coefficient of Responsivity

- The Temperature Coefficient of Responsivity becomes positive above 290 nm, due to the bandgap narrowing and to the enhanced indirect band transitions above this threshold

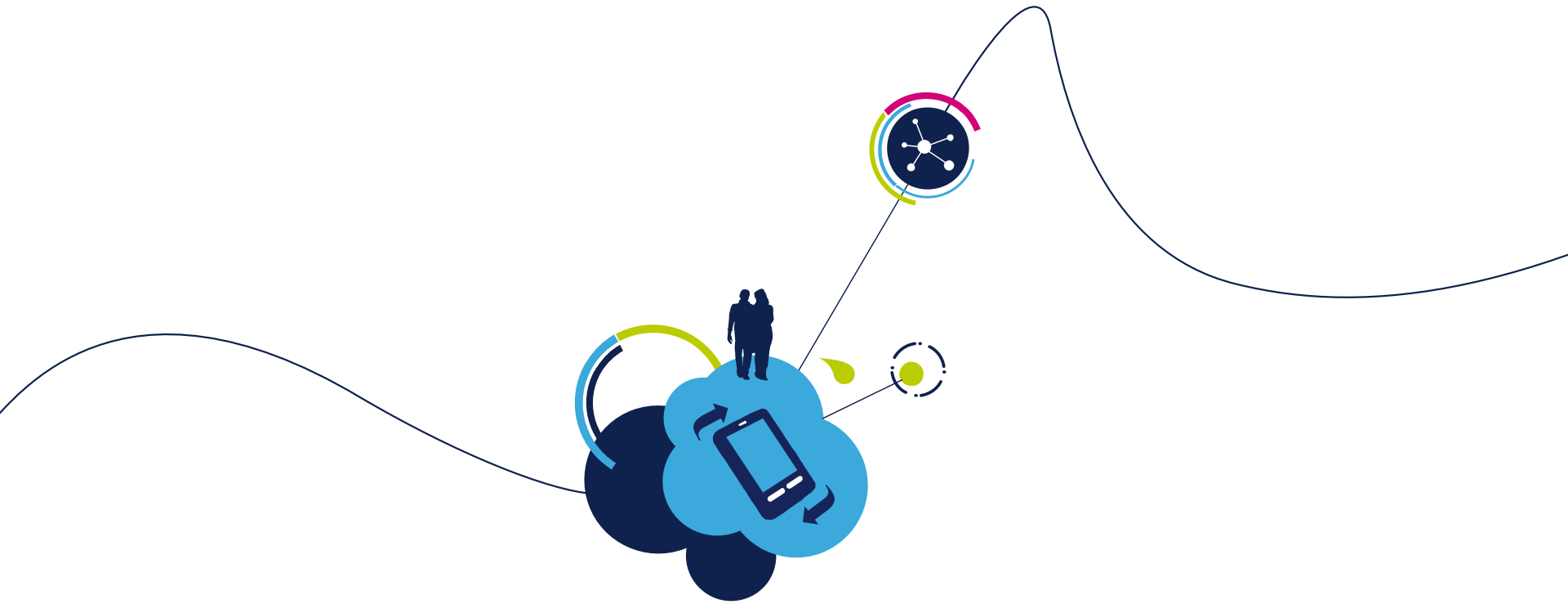


- A suitable 4H-SiC based detector operating in **photovoltaic regime** and coupled to an appropriate IC interface has been developed for the realization of an ultra-compact UVI sensor
- The use of a continuous metal silicide layer allows to obtain a good morphological **reproducibility** and **uniformity** on wafer of the electro-optical detectors performances with high wafer **yield**
- The low leakage current allows to obtain devices with very **high signal-to-noise ratio** and thus able to read with **high efficiency** very low UV photocurrent levels.
- The low thickness of the metal layer on the top side of the photodiodes ensures a **good light transmission** in the UV range enabling an optimal wavelength match with the erythema curve and thus a reliable UV Index evaluation.

Aknowledgements

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Thank you